



Material Content Data Sheet



Sales Product Name				IGB30N60H3		Issued		4. July 2019	
MA#				MA002162692					
Package				PG-TO263-3-2		Weight*		1558.44 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.012	0.19	0.19	1933	1933	
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59		
	non noble metal	iron	7439-89-6	0.304	0.02		195		
	non noble metal	copper	7440-50-8	304.026	19.51	19.54	195083	195337	
	non noble metal	aluminium	7429-90-5	2.696	0.17	0.17	1730	1730	
wire	non noble metal	aluminium	7429-90-5	2.696	0.17	0.17	1730	1730	
encapsulation	organic material	carbon black	1333-86-4	10.304	0.66		6612		
	plastics	epoxy resin	-	113.347	7.27		72731		
	inorganic material	silicondioxide	60676-86-0	563.302	36.16	44.09	361450	440793	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6196	6196	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	147	148	
solder	non noble metal	tin	7440-31-5	0.062	0.00		40		
	noble metal	silver	7440-22-4	0.077	0.00		50		
	non noble metal	lead	7439-92-1	2.957	0.19	0.19	1897	1987	
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		106		
	non noble metal	iron	7439-89-6	0.548	0.04		352		
	non noble metal	copper	7440-50-8	547.666	35.14	35.19	351418	351876	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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